

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/646,897	08/22/2003		Warren M. Farnworth	01-1059.1 1324		
22823	7590	01/27/2005		EXAMINER		
STEPHEN			LEWIS, MONICA			
2764 SOUT		OF STEVE GRAT NWAY	ART UNIT	PAPER NUMBER		
LAKEWOO	D, CO 8	30228	2822			

DATE MAILED: 01/27/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

				1 12				
		Application No.	Applicant(s)	- 0°				
		10/646,897	FARNWORTH ET AL.					
Office Action Summary		Examiner	Art Unit					
		Monica Lewis	2822					
Period	The MAILING DATE of this communication app for Reply	pears on the cover sheet w	ith the correspondence address					
TH - E: af - If - If - F: A	HORTENED STATUTORY PERIOD FOR REPLE MAILING DATE OF THIS COMMUNICATION. Attensions of time may be available under the provisions of 37 CFR 1.1 ter SIX (6) MONTHS from the mailing date of this communication. The period for reply specified above is less than thirty (30) days, a replevion of the period for reply is specified above, the maximum statutory period to allure to reply within the set or extended period for reply will, by statute the property of the period of the peri	36(a). In no event, however, may a r y within the statutory minimum of thir will apply and will expire SIX (6) MON , cause the application to become AE	eply be timely filed by (30) days will be considered timely. ITHS from the mailing date of this communic SANDONED (35 U.S.C. § 133).	eation.				
Status								
1)∑	Responsive to communication(s) filed on 22 A	uaust 2003.						
	- · · _ 	action is non-final.						
3)[ers, prosecution as to the merit	ts is				
-,_	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Dispos	ition of Claims							
4)∑	Claim(s) <u>153-261</u> is/are pending in the applica	tion.						
	4a) Of the above claim(s) is/are withdrawn from consideration.							
5)[Claim(s) is/are allowed.							
6)[Claim(s) is/are rejected.							
7)	Claim(s) is/are objected to.							
8)∑	Claim(s) <u>153-261</u> are subject to restriction and	l/or election requirement.						
Applic	ation Papers		•					
9)[The specification is objected to by the Examine	er.						
10)[10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.							
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
	Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).							
11)[The oath or declaration is objected to by the Ex	caminer. Note the attached	d Office Action or form PTO-152	2.				
Priority	under 35 U.S.C. § 119							
	Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burear See the attached detailed Office action for a list	s have been received. s have been received in A rity documents have been u (PCT Rule 17.2(a)).	pplication No received in this National Stage	ŀ				
Attachm	ent(s)							
	tice of References Cited (PTO-892)		Summary (PTO-413)					
3) 🔲 Inf	tice of Draftsperson's Patent Drawing Review (PTO-948) ormation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) per No(s)/Mail Date	🗂	s)/Mail Date nformal Patent Application (PTO-152)					

DETAILED ACTION

1. This restriction is in response to the application filed August 22, 2003.

Election/Restrictions

2. This application contains claims directed to the following patentably distinct species of the claimed invention:

Embodiment I (Claims 153-179), directed to a semiconductor component, a thinned semiconductor die, a first polymer layer and a second polymer layer; Embodiment II (Claims 180-188), directed to a semiconductor component, a thinned semiconductor die, a circuit side polymer layer, a plurality of edge polymer layers covering four peripheral edges comprising portions of polymer filled trenches and a back side polymer layer;

Embodiment III (Claims 189-195), directed to a semiconductor component, a semiconductor wafer, a thinned substrate, a planarized circuit side polymer layer, a plurality of semiconductor dice separated by streets, a plurality of polymer filled trenches and a planarized back side polymer layer;

Embodiment IV (Claims 196-208), directed to a semiconductor component, a thinned die, die contacts, a circuit side polymer layer covering the circuit side and the four peripheral edges, a plurality of conductive vias, a back side polymer layer, a second polymer layer and a plurality of terminal contacts;

Embodiment V (Claims 209-213), directed to a semiconductor component, a thinned die, a polymer layer covering the circuit side and a heat sink;

Art Unit: 2822

Embodiment VI (Claims 214-219), directed to a semiconductor component, a thinned die, a polymer layer covering the circuit side a polymer tape and a marking in the polymer tape;

Embodiment VII (Claims 220-226), directed to a semiconductor component, a die, die contacts, a polymer layer covering the circuit side, a protective coating covering the edges and the back side and terminal contacts on the die contacts; Embodiment VIII (Claims 227-232), directed to a semiconductor component, a thinned die, die contacts, a polymer layer covering the circuit side comprising a first polymer material and a plurality of second polymer layers covering the peripheral edges comprising a second polymer material;

Embodiment IX (Claims 233-241), directed to a semiconductor component, a thinned die, die contacts comprising pin contacts, conductive vias and a plurality of terminal contacts;

Embodiment X (Claims 242-248), directed to a semiconductor component, a thinned die, die contacts comprising tip potions, conductive vias, a plurality of terminal contacts in electrical communication with the vias, a plurality of conductors and a plurality of terminal contacts in electrical communication with the conductors;

Embodiment XI (Claims 249-255), directed to a semiconductor component, a substrate, a thinned die, a first polymer layer covering the circuit side and the edges, a second polymer layer covering the back side and a plurality of terminal

Art Unit: 2822

contacts on the first polymer layer in electrical communication with the die and bonded to the substrate;

Embodiment XII (Claims 256-258), directed to a semiconductor component, a substrate comprising a plurality of terminal leads, a component mounted to the substrate, a thinned die, die contacts, contact bumps, a first polymer layer covering the circuit side the edges and contact bumps, a second polymer layer covering the back side, a plurality of terminal contacts on the contact bumps and a plastic body; and

Embodiment XIII (Claims 259-261), directed to a semiconductor component, a substrate comprising a plurality of terminal leads, a component mounted to the substrate, a thinned die, die contacts, contact bumps, a first polymer layer covering the circuit side the edges and contact bumps, a second polymer layer covering the back side, a plurality of conductive vias, a plurality of terminal contacts and a second semiconductor component substantially identical to the first component comprising second terminal contacts bonded to the contact bumps.

Applicant is required under 35 U.S.C. 121 to elect a single disclosed species for prosecution on the merits to which the claims shall be restricted if no generic claim is finally held to be allowable. Currently, none are generic.

Applicant is advised that a reply to this requirement must include an identification of the species that is elected consonant with this requirement, and a listing of all claims readable thereon, including any claims subsequently added. An argument that a claim is allowable or that all claims are generic is considered nonresponsive unless accompanied by an election.

Art Unit: 2822

Upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which are written in dependent form or otherwise include all the limitations of an allowed generic claim as provided by 37 CFR 1.141. If claims are added after the election, applicant must indicate which are readable upon the elected species. MPEP § 809.02(a).

Should applicant traverse on the ground that the species are not patentably distinct, applicant should submit evidence or identify such evidence now of record showing the species to be obvious variants or clearly admit on the record that this is the case. In either instance, if the examiner finds one of the inventions unpatentable over the prior art, the evidence or admission may be used in a rejection under 35 U.S.C. 103(a) of the other invention.

3. Applicant is reminded that upon the cancellation of claims to a non-elected invention, the inventorship must be amended in compliance with 37 CFR 1.48(b) if one of the currently named inventors is no longer an inventor of at least one claim remaining in the application. Any amendment of inventorship must be accompanied by a request under 37 CFR 1.48(b) and by the fee under 37 CFR 1.17(i).

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica Lewis whose telephone number is 571-272-1838.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-308-7722 for regular and after final

Art Unit: 2822

communications. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML

January 11, 2005

Mary Wilczewski Primary Examiner